ABSTRACT OF THE DISCLOSURE

This bonding device 1 is provided with: a tape feeder module 10 which takes out an electronic component 301 from a carrier tape 13 and transfers the electronic component 301 thus taken out; a die supply module 20 which has a die pick-up mechanism 21 for picking up a semiconductor die 201 from a semiconductor wafer 200 bonded to a dicing sheet 22a by pushing up the semiconductor die 201 and which transfers the semiconductor die 201 thus picked up; and a bonding module 40 which disposes, on a circuit substrate 101, the semiconductor die 201 provided by the die supply module 20 and/or the electronic component 301 provided by the tape feeder module 10.

FIG. 1